Impel Plus Backplane Connectors and Cable Assemblies



Impel Plus Backplane Connector System achieves data rates up to 56 Gbps with superior signal integrity performance and enables backward and forward compatibility with compact compliant pins

Features and Advantages

Compact, compliant-pin 56-Gbps backplane connector

Enables backward and forward compatibility with various high-end copper and cable architectures



Offers better signal integrity performance due to shallow PCB hole. Lowers PCB costs by reducing layers



Impel Plus 3-Pair, Right-Angle Daughtercard, 1.90mm Pitch

Small compliant pin $(0.31 \text{mm} \pm -0.05)$

Reduces crosstalk by enabling optimized routing or use of pinning via

92 Ohms nominal impendence

Minimizes impedance discontinuities in the channel

Molex patent-pending Impel Connector technology with tightly coupled differential-pair structure

Provides optimal signal integrity and mechanical isolation through the connector system

Innovative signal beam interface

Improves insertion loss compared to in-line signal beams. Pushes interface resonance frequency past 30 GHz





Impel Plus 3-Pair, 2.35mm-Pitch Right-Angle Orthogonal Direct Connector System

Grounding tail aligner for lead frames and wafer shields closer to daughtercard launch to improve ground return path Minimizes impedance discontinuities. Reduces crosstalk

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IEEE 10GBASE-KR and Optical Internetworking Forum (OIF) Stat Eye Compliant Channel

Demonstrates end-to-end channel performance compliance

3-, 4- and 6-pair daughtercards available with a range of column sizes Delivers design flexibility



Impel Plus 4-Pair, Right-Angle Daughtercard, 1.90mm Pitch

High-speed automation line is available for high-volume production of cable

Controlled manufacturing process provides cables with reliable and consistent signal integrity performance

Cable Accomblise Available with Impel Plus 3- 4- and accom

Cable Assemblies Available with Impel Plus 3-, 4- and 6-Pair Daughtercards and Impel Cables (Assembly with Impel 6-Pair Daughtercard pictured) Complete mechanical, electrical and testing capabilities available to deliver a complete backplane solution

Offers value-added cable trays

Assemblies with Impel Cables up to 3.0m long can be configured with 3-, 4- and 6-pair Impel Plus Daughtercards

Supports design flexibility to maximize density of differential pairs with cables

Impel Plus Backplane Connectors and Cable Assemblies



Applications

Telecommunications/Networking

Servers

Switches

Routers

Data Center Solutions

Servers

Storage Systems

Medical

Patient monitoring



High-End Server

Specifications

REFERENCE INFORMATION

Packaging: Tray UL File No.:

Mates With: Impel Vertical Backplane Headers (see

other available Impel header options)

OD Daughtercard (Series 171510) mates with OD

Header (Series 173460) Designed In: Millimeters

RoHS: Yes Halogen Free: Yes

ELECTRICAL

Electrical

Voltage (max):150V AC RMS Current (max): 0.75A

Contact Resistance: 100mA; 20mV Dielectric Withstanding Voltage: 500V AC

Insulation Resistance: 500V

MECHANICAL

Insertion Force to PCB (max.): 26.69N per tail Mating Force: 60g per signal; 80g per shield

Unmating Force (min.): 60g Durability (min.): 200 Cycles

PHYSICAL

Housing: LCP Contact: Copper Alloy

Plating:

Contact Area — $0.76~\mu m$ (30μ ") Gold (Au) Solder Tail Area — select Matte Tin (Sn)

Underplating — Nickel (Ni)
PCB Thickness (min.): 1.00mm
Operating Temperature: -55° to +85°C

Ordering Information

Series No.	Component	Pitch (mm)	Number of Pairs
<u>172730</u>	Daughtercard -	1.9	3
<u>204066</u>		1.9	4

Series No.	Component	Orientation	Pitch (mm)	Number of Pairs
<u>171510</u>	Orthogonal Direct Daughtercard	Right Angle	0.05	
<u>173460</u>	Orthogonal Direct Header		2.35	3

Series No.	Component	Pitch (mm)	Number of Pairs
Contact Malay	Daughtercard -	3	4
Contact Molex		1.9	6

Custom Product	Description
Contact Molex	Assemblies with Impel Plus Daughtercard and Impel Cables

www.molex.com/link/impel.html